

AMENDMENTS TO THE CLAIMS, COMPLETE LISTING OF CLAIMS
IN ASCENDING ORDER WITH STATUS INDICATOR

Please amend the following claims as indicated.

1. (Currently Amended) A process for a molded article which is shaped by molding, comprising:

shaping a material comprising aA thermosetting resin composition containing 100 parts by weight of a thermosetting resin and 0.1 to 100 parts by weight of an inorganic compound dispersed in said thermosetting resin in a die by transferring a shape of the die the inorganic compound being at least one of silica and laminar silicate, and~~characterized in that~~ the dispersion particle diameter of the silica beingsaid inorganic compound is 2 μ m or less and the laminar silicate having an average length of 0.01 to 3 μ m and;

curing the material after shaping to obtain the molded article wherein not less than 75% of the shape of thean article molded before curing is maintained after the resin composition is cured.

2. (Currently Amended) The thermosetting resin composition process for a molded article according to claim 1, wherein said inorganic compound is an inorganic compound containing silicon and oxygen as a constituent ~~element~~ elements.

3. (Currently Amended) The thermosetting resin composition process for a molded article according to claim 1 or 2, wherein said inorganic compound is laminar silicate.

4. (Currently Amended) The thermosetting resin composition process for a molded article according to claim 1 ~~or 2~~, wherein said resin composition contains an epoxy resin as said thermosetting resin.

5. (Currently Amended) ~~A material for substrates, characterized in that said material is composed by using the thermosetting resin composition~~ substrate comprising the molded article obtained by the process for the molded article according to claim 1 or ~~2~~ 4.

6. (Currently Amended) A film for substrates, ~~characterized in that said film is composed by using the thermosetting resin composition~~ comprising the molded article obtained by the process for the molded article according to claim 1 or ~~2~~ 4.

7. (Currently Amended) ~~The thermosetting resin composition~~ process for a molded article according to claim 3, wherein said resin composition contains an epoxy resin as said thermosetting resin.

8. (Currently Amended) ~~A material for substrates, characterized in that said material is composed by using the thermosetting resin composition~~ substrate comprising the molded article obtained by the process for the molded article according to claim 3.

9. (Currently Amended) ~~A material for substrates, characterized in that said material is composed by using the thermosetting resin composition~~ substrate comprising the molded article obtained by the process for the molded article according to claim 4.

10. (Currently Amended) A film for substrates, ~~characterized in that said film is composed by using the thermosetting resin composition~~ substrate comprising the molded article obtained by the process for the molded article according to claim 3.

11. (Currently Amended) A film for substrates, ~~characterized in that said film is composed by using the thermosetting resin composition~~ substrate comprising the molded article obtained by the process for the molded article according to claim 4.